

Abstract

The invention relates to processes for producing copy protection for an integrated circuit.

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To avoid unauthorized copying of an integrated circuit, it is an object of the invention to provide an effective and reliable copy protection.

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The invention proposes a process comprising the steps of providing a substrate (1) which has semiconductor structures (2) on at least a first side (1a) of the substrate (1), providing a material (23) for coating the substrate (1), coating the substrate (1) with a copy-protect layer (4).

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It has proven particularly advantageous for the copy-protect layer (4) to be produced by applying a silicate glass by evaporation coating, since this means that an etching process which dissolves the copy-protect layer also attacks the substrate (1), in such a manner that the semiconductor structures (2) are at least partially destroyed.

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